



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg
Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Jan 08, 2016
Contact Name * Jolene Small	Title - Contact Product Ecology	Phone - Contact * 207-761-6214	Email - Contact * jolene.small @fairchildsemi.com
Authorized Representative * Jolene Small	Title - Representative Product Ecology	Phone - Representative * 207-761-6214	Email - Representative * jolene.small@fairchildsemi.com


Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	FSC Version	Manufacturing Site	Weight*	UOM	Unit Type
FNA27560	FNA27560	SPMCA-34	Jan 08, 2016	1.0	FSSZ	49.619758	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	NA	Not Applicable		Not Applicable

* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions Supplier Acceptance * Accepted		
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
<div style="margin-left: 20px;">Exemption List Version EL-2011/534/EU</div> <div style="margin-left: 20px;">7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).</div>		

Declaration Signature	
Supplier Signature	<div style="text-align: center;">  JOLENE SMALL – PRODUCT ECOLOGY ENGINEER </div>

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SPMCA-34.csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Silicon and inorganic compounds	104.6	Supplier	-	Silicon	104.6	7440-21-3	2108
Die Attach Epoxy	Other Organic Materials	1.85	Supplier	-	Phenolic resin (in DA)	0.15	54208-63-8	3
			Supplier	-	Silver	1.7	7440-22-4	34
Die Attach Paste	Other Organic Materials	200	Supplier	-	Silver	10	7440-22-4	202
			Supplier	-	Tin	190	7440-31-5	3829
Die Attach Solder	Solder	1.7	A	Lead/Lead Compounds	Lead	0.085	7439-92-1	2
			Supplier	-	Silver	1.5725	7440-22-4	32
			Supplier	-	Tin	0.0425	7440-31-5	1
Encapsulation	Epoxy	31430	Supplier	-	Carbon Black	314.3	1333-86-4	6334
			Supplier	-	Epoxy Resin	1571.5	29690-82-2	31671
			Supplier	-	Phenolic resin (in MC)	1571.5	9003-35-4	31671
			Supplier	-	Silica, vitreous	27972.7	60676-86-0	563741
Heat Sink	Ceramics / Glass	6642	Supplier	-	Aluminum Oxide	6642	1344-28-1	133858
Lead Frame	Copper Alloy	11022.545	Supplier	-	Copper	11000.5	7440-50-8	221696
			Supplier	-	Iron	16.5338	7439-89-6	333
			Supplier	-	Phosphorus	5.51125	7723-14-0	111
NTC	Other Organic Materials	10	Supplier	-	Sub components NTC	10	component	202
Plating	Other Nonferrous metals & alloys	106.6	Supplier	-	Tin	106.6	7440-31-5	2148
Wire Bond - Al	Precious metals	100	Supplier	-	Aluminum	100	7429-90-5	2015
Wire Bond - Cu	Copper Wire	0.463	Supplier	-	Copper	0.463	7440-50-8	9